

Resonac Photonics Corporation Marketing Department

Email: RPC Elled@resonac.com

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1. Color Infrared 2 Materials GaAs/GaAs

3. Electrode P(anode) side : Al

N(cathode) side: Au

4. Electrode pattern Fig.1,2

5. Chip size 0.185mm X 0.185mm X 0.180mmH (Fig.1)

6. Emission area 0.160mm X .160mm (Fig.1)

7. Electro-Optical characteristics

Parameters	Symbol	Condition	Min	Тур	Max	Unit
Power	Po	IF=20mA	0.4	0.75	_	mW
Forward Voltage	VF	IF=20mA	_	1.3	1.5	V
Reverse Current	IR	VR=5V	_	_	10	uA
Peak Wavelength	* λp	IF=20mA	_	940	_	nm
Spectral Radiation Bandwidth	* Δλ	IF=20mA	_	40	_	nm

- [*] mark is reference data
- Power measurement at Resonac Photonics.
- 8. Recommended bonding method Ultra-sonic method or a combination of ultra-sonic and thermo-compression methods.

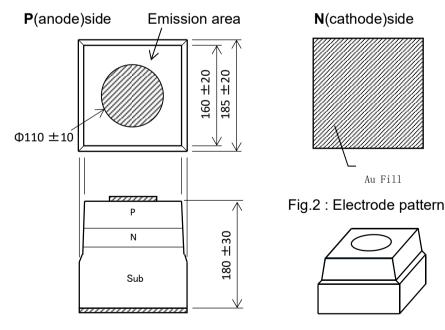


Fig.1: Chip size and Emission area

Fig.3: No roughing

Au Fill

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However, no representations, guaranties or warranties of any kind are made as to accuracy and suitability of the Product for particular applications or the results of its use.

Resonac Photonics Corporation reserves the right to introduce changes without notice.